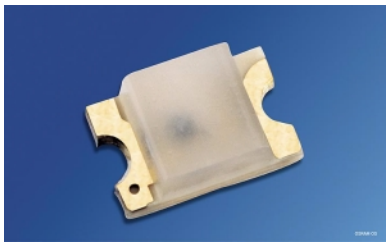
CHIPLED

LO R971, LY R971



Besondere Merkmale

- **Gehäusetyp:** 0805
- **Besonderheit des Bauteils:** extrem kleine Bauform 2,0 mm x 1,25 mm x 0,8 mm
- **Wellenlänge:** 590 nm (gelb), 605 nm (orange)
- **Abstrahlwinkel:** extrem breite Abstrahlcharakteristik (160°)
- **Technologie:** GaAsP (gelb, orange)
- **optischer Wirkungsgrad:** 1,5 lm/W (gelb), 1,5 lm/W (orange)
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 8 mm Gurt mit 4000/Rolle, ø180 mm

Features

- **package:** 0805
- **feature of the device:** extremely small package 2.0 mm x 1.25 mm x 0.8 mm
- **wavelength:** 590 nm (yellow), 605 nm (orange)
- **viewing angle:** extremely wide (160°)
- **technology:** GaAsP (yellow, orange)
- **optical efficiency:** 1.5 lm/W (yellow), 1.5 lm/W (orange)
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 8 mm tape with 4000/reel, ø180 mm

Anwendungen

- Informationsanzeigen im Innenbereich
- optischer Indikator
- Flache Hinterleuchtung (LCD, Handy, Schalter, Display)
- Spielsachen

Applications

- indoor displays
- optical indicators
- flat backlighting (LCD, cellular phones, switches, displays)
- toys

Typ Type	Emissionsfarbe Color of Emission	Farbe der Lichtaustritts-fläche Color of the Light Emitting Area	Lichtstärke Luminous Intensity I_F = 20 mA I_V (mcd)		Bestellnummer Ordering Code
			min.	typ.	
LO R971	orange	colorless diffused	2.8	6	Q62702-P5180
LY R971	yellow	colorless diffused	2.8	6	Q62702-P5181

Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von ±11 % ermittelt.
Luminous intensity is tested at a current pulse duration of 25 ms and an accuracy of ±11 %.

Anm.: Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 3 bzw. 4 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.
In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.

Note: The standard shipping format for serial types includes a lower or upper family group of 3 or 4 individual groups. Individual half groups are not available.
No packing unit / tape ever contains more than one luminous intensity group.

Grenzwerte
Maximum Ratings

Bezeichnung **Parameter**	**Symbol** **Symbol**	**Wert** **Value**	**Einheit** **Unit**
Betriebstemperatur Operating temperature range	T_{op}	– 30 … + 85	°C
Lagertemperatur Storage temperature range	T_{stg}	– 40 … + 85	°C
Sperrschichttemperatur Junction temperature	T_j	+ 95	°C
Durchlassstrom Forward current	I_F	25 (orange) 20 (yellow)	mA
Stoßstrom Surge current $t_p = 10$ µs, $D = 0.1$	I_{FM}	0.1	A
Sperrspannung Reverse voltage	V_R	5	V
Leistungsaufnahme Power consumption	P_{tot}	65	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient Sperrschicht/Lötpad Junction/solder point Montage auf PC-Board FR 4 (Padgröße ≥ 16 mm²) mounted on PC board FR 4 (pad size ≥ 16 mm²)	 $R_{th\ JA}$ $R_{th\ JS}$	 800 450	 K/W K/W

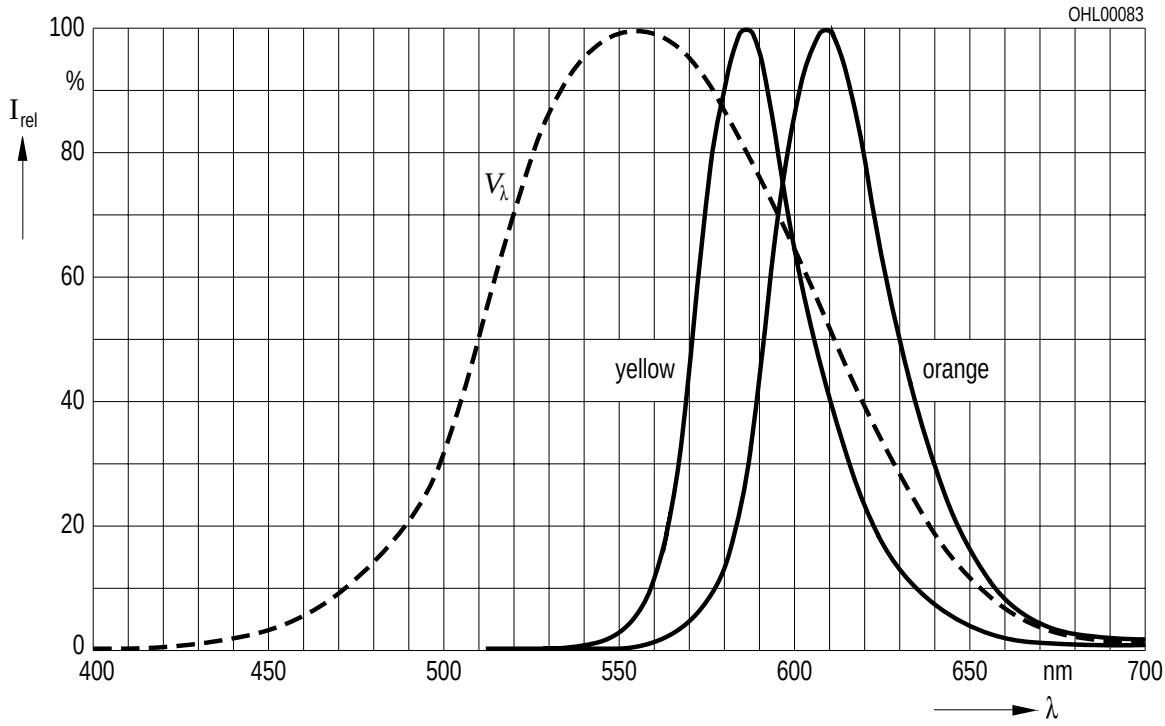
Kennwerte (T_A = 25 °C)
Characteristics

Bezeichnung **Parameter**		**Symbol** **Symbol**	**Werte** **Values**		**Einheit** **Unit**
			LO	**LY**	
Wellenlänge des emittierten Lichtes Wavelength at peak emission I_F = 20 mA	(typ.)	λ_{peak}	610	589	nm
Dominantwellenlänge [1] Dominant wavelength [1] I_F = 20 mA	(typ.)	λ_{dom}	605	590	nm
Spektrale Bandbreite Spectral bandwidth I_F = 20 mA	(typ.)	$\Delta\lambda$	35	40	nm
Abstrahlwinkel bei 50 % I_V (Vollwinkel) Viewing angle at 50 % I_V	(typ.)	2φ	160	160	Grad deg.
Durchlassspannung [2] Forward voltage [2] I_F = 20 mA	(typ.) (max.)	V_F V_F	2.1 2.5	2.2 2.5	V V
Sperrstrom Reverse current V_R = 5 V	(typ.) (max.)	I_R I_R	0.02 100	0.02 100	µA µA
Temperaturkoeffizient von λ_{peak} Temperature coefficient of λ_{peak} I_F = 20 mA; –10°C ≤ T ≤ 100°C	(typ.)	$TC_{\lambda peak}$	0.11	0.11	nm/K
Temperaturkoeffizient von λ_{dom} Temperature coefficient of λ_{dom} I_F = 20 mA; –10°C ≤ T ≤ 100°C	(typ.)	$TC_{\lambda dom}$	0.06	0.08	nm/K
Temperaturkoeffizient von V_F Temperature coefficient of V_F I_F = 20 mA; –10°C ≤ T ≤ 100°C	(typ.)	TC_V	– 1.6	– 1.7	mV/K
Optischer Wirkungsgrad Optical efficiency I_F = 20 mA	(typ.)	η_{opt}	1.5	1.5	lm/W

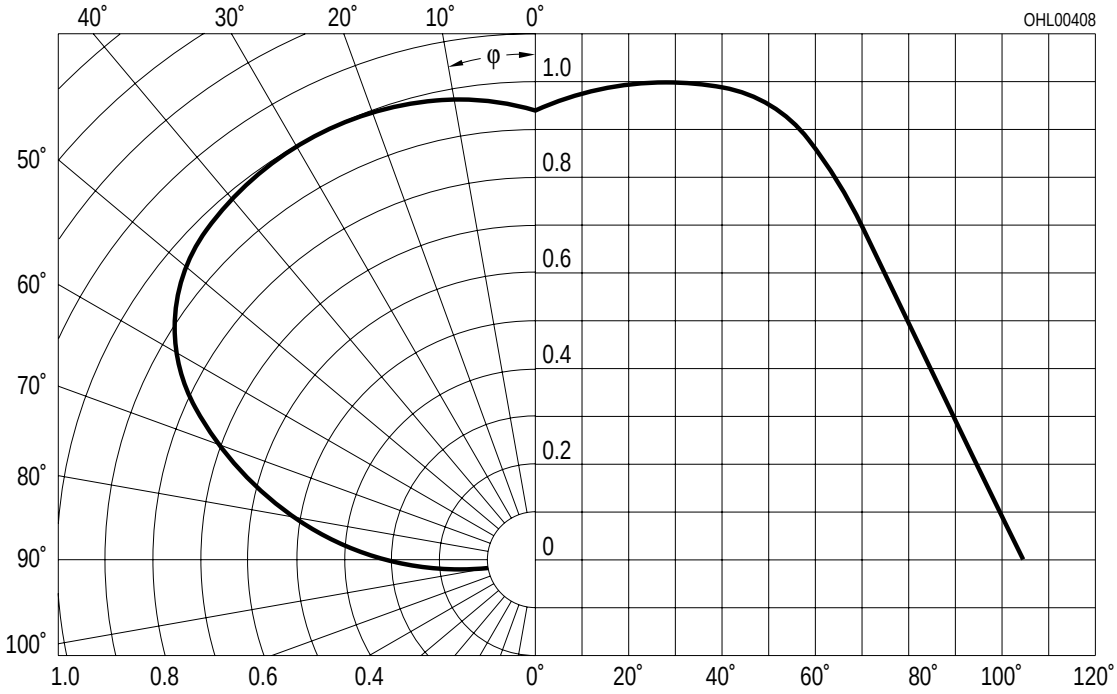
[1] Wellenlängengruppen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von ±1 nm ermittelt.
Wavelength groups are tested at a current pulse duration of 25 ms and an accuracy of ±1 nm.

[2] Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von ±0,1 V ermittelt.
Voltages are tested at a current pulse duration of 1 ms and an accuracy of ±0.1 V.

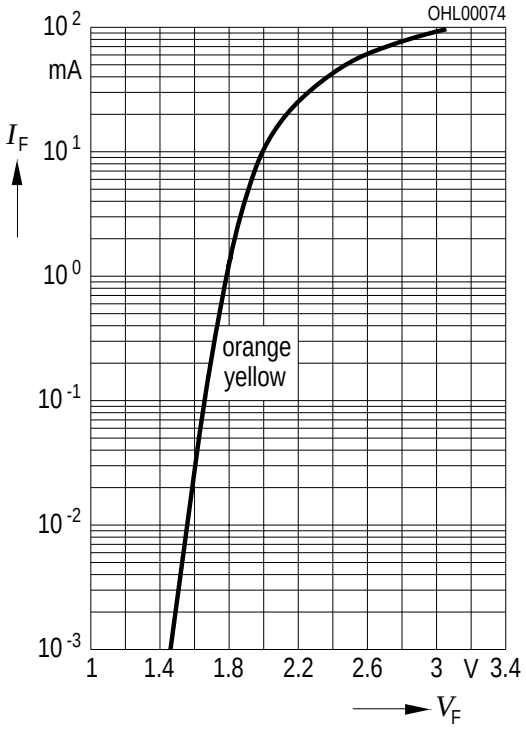
Relative spektrale Emission $I_{rel} = f(\lambda)$, T_A = 25 °C, I_F = 20 mA
Relative Spectral Emission
V(λ) = spektrale Augenempfindlichkeit
Standard eye response curve



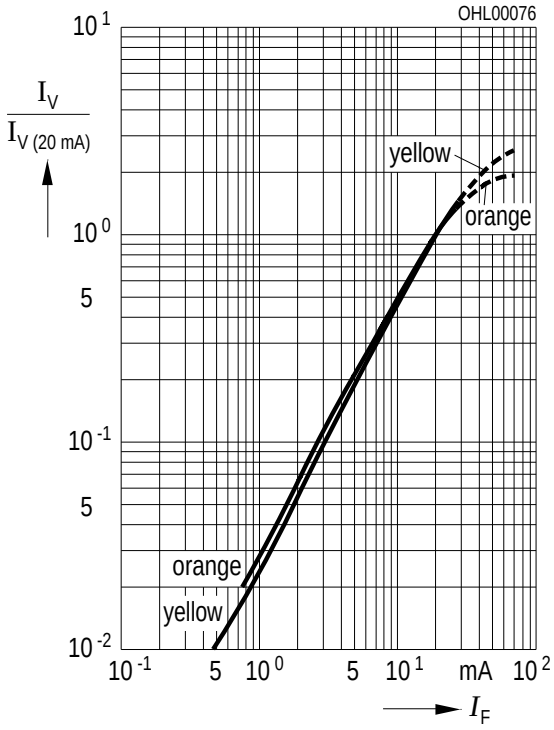
Abstrahlcharakteristik $I_{rel} = f(\varphi)$
Radiation Characteristic



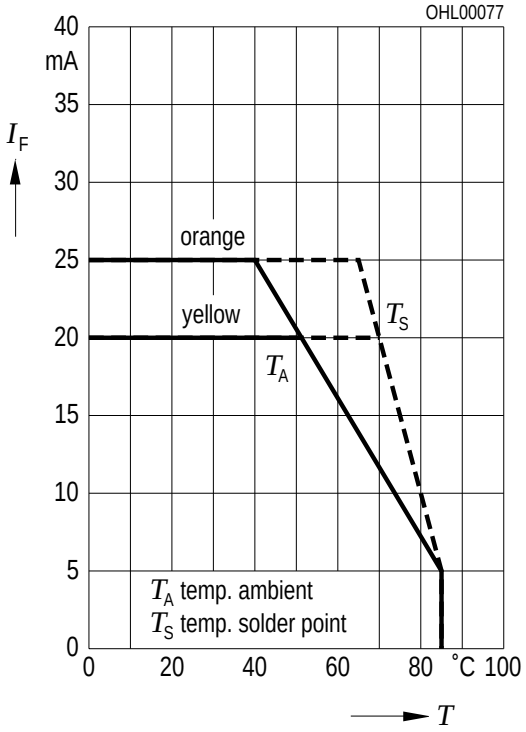
Durchlassstrom $I_F = f(V_F)$
Forward Current
T_A = 25 °C



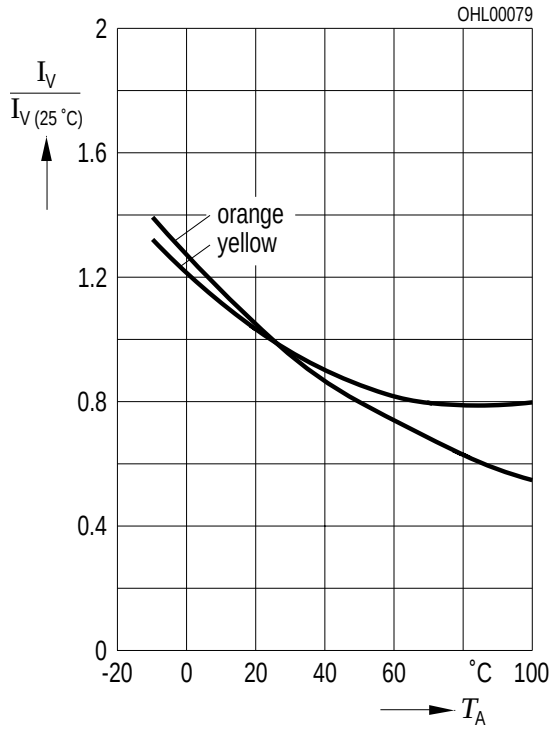
Relative Lichtstärke $I_V/I_{V(20\ mA)} = f(I_F)$
Relative Luminous Intensity
T_A = 25 °C



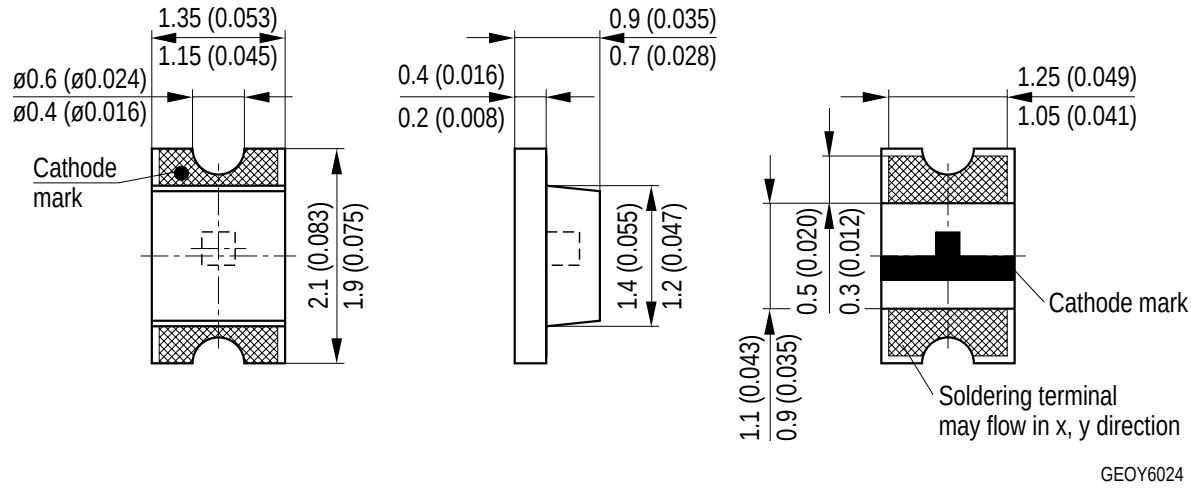
Maximal zulässiger Durchlassstrom $I_F = f(T_A)$
Max. Permissible Forward Current



Relative Lichtstärke $I_V/I_{V(25\ °C)} = f(T_A)$
Relative Luminous Intensity
I_F = 20 mA



Maßzeichnung
Package Outlines

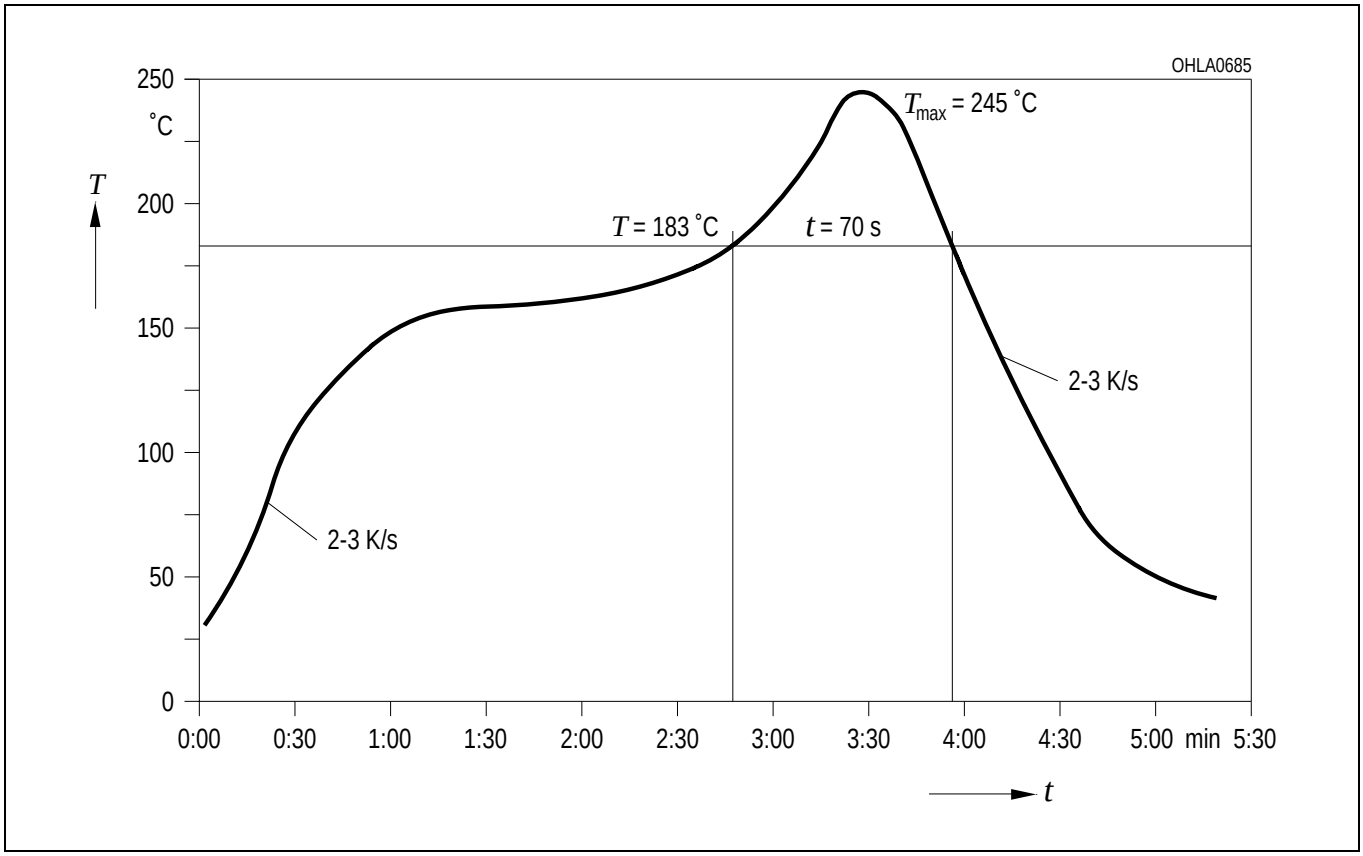


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

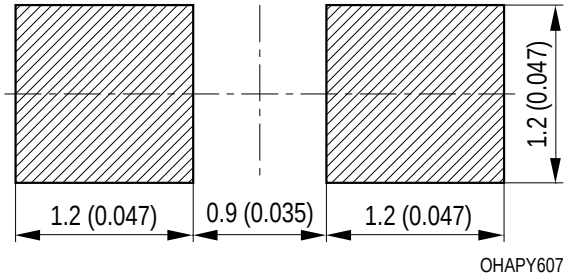
Gewicht / Approx. weight: 3.2 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)

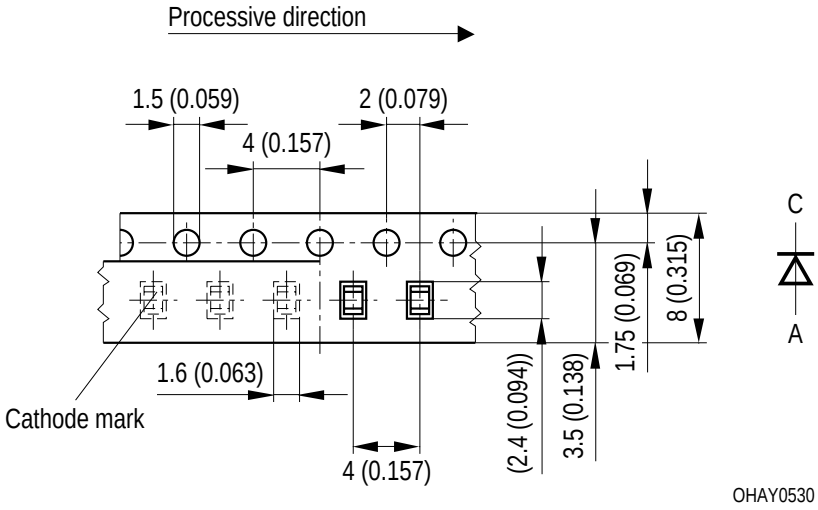


Empfohlenes Lötpaddesign IR Reflow Löten
Recommended Solder Pad IR Reflow Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Gurtung / Polarität und Lage Verpackungseinheit 4000/Rolle, ø180 mm
Method of Taping / Polarity and Orientation Packing unit 4000/reel, ø180 mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2001-03-05	
Previous Version: 2001-03-05	
Page	**Subjects (major changes since last revision)**

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